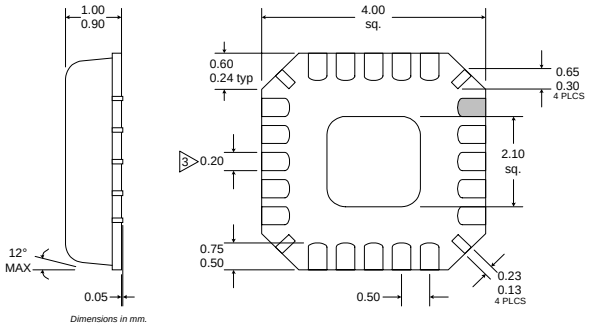
W-CDMA AND PCS LOW NOISE AMPLIFIER/MIXER DOWNCONVERTER

Typical Applications

- W-CDMA Handsets
- PCS Handsets
- General Purpose Downconverter
- Commercial and Consumer Systems
- Portable Battery-Powered Equipment

Product Description

The RF2469 is a receiver front-end designed for the receive section of W-CDMA and PCS applications. It is designed to amplify and downconvert RF signals while providing 20dB of stepped gain control range and features digital control of the LNA gain and power down mode. A further feature of the chip is adjustable IIP3 of the LNA and mixer using an off-chip current setting resistor. Noise Figure, IP3, and other specs are designed to be compatible with W-CDMA and PCS communications. The IC is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (GaAs HBT) process and packaged in a 20-pin, leadless chip carrier with an exposed die flag.

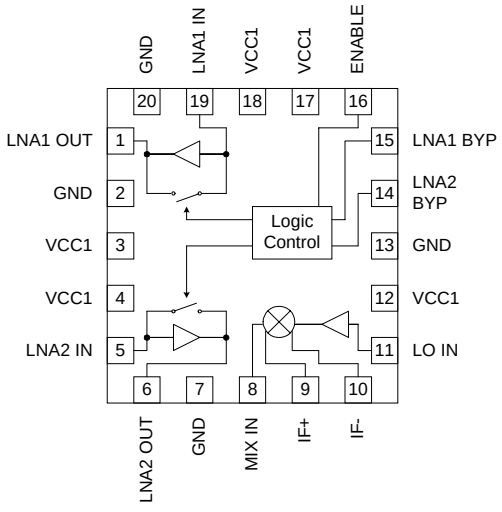


NOTES:
1. Shaded lead is Pin 1.
2. Pin 1 identifier must exist on top surface of package by identification mark or feature on the package body. Exact shape and size is optional.
3. Dimension applies to plated terminal: to be measured between 0.02 mm and 0.25 mm from terminal end.
4. Package Warpage: 0.05 mm max.
5. Die Thickness Allowable: 0.305 mm max.

Package Style: Leadless Chip Carrier, 20-Pin

Optimum Technology Matching® Applied

- ☐ Si BJT
- ☑ GaAs HBT
- ☐ GaAs MESFET
- ☐ Si Bi-CMOS
- ☐ SiGe HBT
- ☐ Si CMOS



Functional Block Diagram

Features

- Complete Receiver Front-End
- Stepped LNA/Mixer Gain Control
- Adjustable LNA/Mixer Bias Current
- 23dB Maximum Cascade Gain
- 2.5dB Noise Figure at Maximum Cascade Gain

Ordering Information

RF2469	W-CDMA and PCS Low Noise Amplifier/Mixer Downconverter
RF2469 PCBA	Fully Assembled Evaluation Board

RF Micro Devices, Inc.
7625 Thorndike Road
Greensboro, NC 27409, USA
Tel (336) 664 1233
Fax (336) 664 0454
http://www.rfmd.com

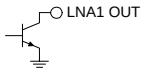
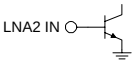
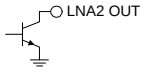
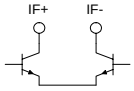
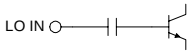
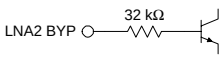
Absolute Maximum Ratings

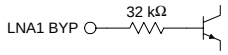
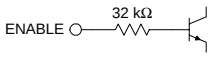
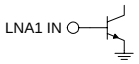
Parameter	Rating	Unit
Operating Ambient Temperature	-40 to +85	℃
Storage Temperature	-40 to +150	℃

Caution! ESD sensitive device.

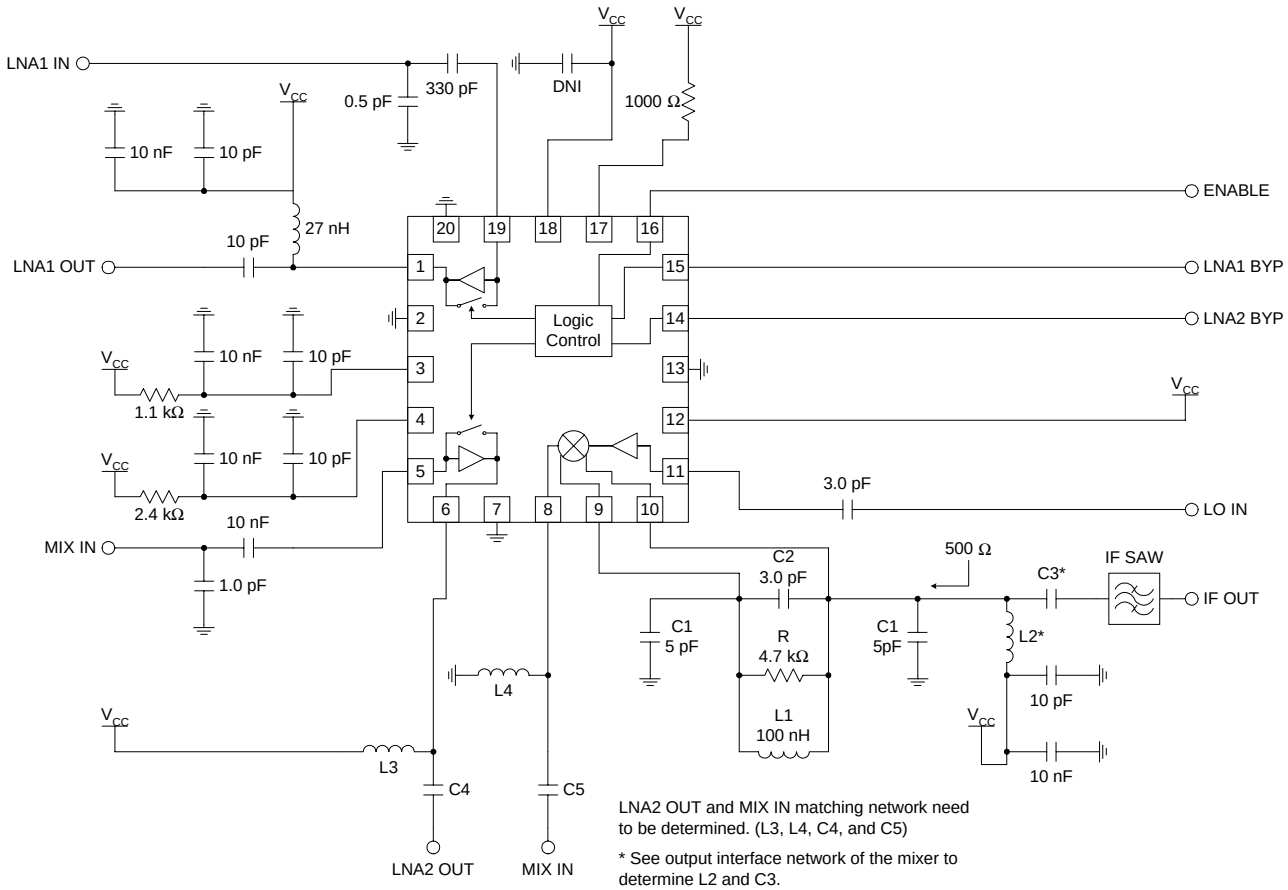
Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Overall					T=25°C, V_{CC}=2.78V, RF=2140MHz, LO=2330MHz @ -10dBm
RF Frequency Range		2110 to 2170		MHz	
LO Frequency Range		2300 to 2360		MHz	
IF Frequency Range		190		MHz	
LNA 1					1st LNA current setting resistor (R1) is 1.1kΩ. 1st LNA current and IIP3 are adjustable via R1.
Gain	9	10	11	dB	
Noise Figure		1.45	1.6	dB	
Input IP3	10	12		dBm	
Input VSWR		<2:1			
Output VSWR		<2:1			
P1dB		-3		dB	
Current		4.5		mA	
LNA 1 Bypass					
Gain	-3	-2		dB	
Noise Figure		2		dB	
Input IP3		+20		dBm	
Input VSWR		<2:1			
Output VSWR		<2:1			
Current		1.6		mA	
Local Oscillator Input					Single-ended. Optimum LO Drive -10dBm to -5dBm.
Input Level		-10		dBm	
LO to IF Isolation		+38		dB	
Mixer/LNA2 BYP High					T=25°C, V_{CC}=2.78V, RF=2140MHz, LO=2330MHz @ -10dBm
Gain		17		dB	
Noise Figure		4.5		dB	
Input IP3		-2		dBm	LNA 2 current setting resistor (R2) is 2.4kΩ
Input IP2		+15		dBm	LNA 2 current and IIP3 are adjustable via R2.
Mixer/LNA2 BYP Low					T=25°C, V_{CC}=2.78V, RF=2140MHz
Gain		6		dB	
Noise Figure		10.5		dB	
Input IP3		8		dBm	LNA 2 current setting resistor (R2) is 2.4kΩ
Input IP2		+25		dBm	LNA 2 current and IIP3 are adjustable via R2.

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Cascade - Condition 1					LNA1 BYP high, LNA2 BYP high, ENABLE high. Assuming 2.5dB filter loss.
Gain		24.5		dB	
Noise Figure		2.55		dB	
Input IP3		-9.5		dBm	
Current Consumption		18.6		mA	
Cascade - Condition 2					LNA1 BYP high, LNA2 BYP low, ENABLE high. Assuming 2.5dB filter loss.
Gain		13.5		dB	
Noise Figure		5.1		dB	
Input IP3		0.2		dBm	
Current Consumption		17		mA	
Cascade - Condition 3					LNA1 BYP low, LNA2 BYP high, ENABLE high. Assuming 2.5dB filter loss.
Gain		12.5		dB	
Noise Figure		9		dB	
Input IP3		2.4		dBm	
Current Consumption		14		mA	
Cascade - Condition 4					LNA1 BYP low, LNA2 BYP low, ENABLE low. Assuming 2.5dB filter loss.
Gain		1.50		dB	
Noise Figure		15		dB	
Input IP3		11.8		dBm	
Current Consumption		7		mA	
Power Supply					
Voltage	2.7	2.75	3.3	V	

Pin	Function	Description	Interface Schematic
1	LNA1 OUT	LNA output pin. This is an open-collector output. Externally matched to 50Ω.	
2	GND	This pin is connected to the ground plane.	
3	VCC1	Supply voltage for LNA1. An external resistor is placed in series with this pin to adjust the current and IIP3 of LNA1. A nominal value of 1.1kΩ sets the LNA1 current to 4.5mA with a minimum IIP3 of +10dBm. External RF bypassing is required. The trace length between the bypass caps and the pin should be minimized. Connect ground sides of caps directly to ground.	
4	VCC1	Supply voltage for LNA2. An external resistor is placed in series with this pin to adjust the current and IIP3 of LNA2. A nominal value of 2.4kΩ sets the LNA2 current to 1.6mA with a typical IIP3 of +10dBm. External RF bypassing is required. The trace length between the bypass caps and the pin should be minimized. Connect ground sides of caps directly to ground.	
5	LNA2 IN	RF input to LNA2. This pin is internally DC biased and, if it is connected to a device with DC present, should be DC blocked with a capacitor suitable for the frequency of operation.	
6	LNA2 OUT	LNA output pin. This is an open-collector output. In normal operation, this pin is externally cascaded with pin 8 (MIX IN).	
7	GND	Ground connection. For best performance, keep traces physically short and connect directly to ground plane.	
8	MIX IN	Mixer RF input pin. This pin requires a DC path to ground. In normal operation, this pin is externally cascaded with pin 6 (LNA2 OUT). The external match ensures a conjugate match between pin 6 and pin 8 while providing a DC path to ground for pin 8 and a DC block between pin 8 and pin 6.	
9	IF+	IF output pin. The output is balanced. A current combiner external network performs a differential to single-ended conversion and sets the output impedance. There must be a DC path from Vcc to this pin. This is normally achieved with the current combiner network. A DC blocking cap must be present if the IF filter input has a DC path to ground.	
10	IF-	Same as pin 9, except complementary output.	See pin 9.
11	LO IN	Mixer LO single-ended input. The pin is internally DC blocked. External matching sets impedance.	
12	VCC1	Supply voltage for LO buffer. External RF bypassing is required. The trace length between the bypass caps and the pin should be minimized. Connect ground sides of caps directly to ground.	
13	GND	This pin is connected to the ground plane.	
14	LNA2 BYP	Logic control for LNA2 gain. A logic high (≥2.4V) places LNA2 in the high gain mode. A logic low (≤0.3V) place LNA2 in the bypass mode.	

Pin	Function	Description	Interface Schematic
15	LNA1 BYP	Logic control for LNA1 gain. A logic high (≥2.4V) places LNA1 in the high gain mode. A logic low (≤0.3V) place LNA1 in the bypass mode.	
16	ENABLE	A logic control for mixer and LO buffer. A logic high (≥2.4V) turn the mixer and LO buffer on. A logic low (≤0.3V) disable the mixer and LO buffer.	
17	VCC1	Supply voltage for the mixer. An external resistor is place in series with this pin to adjust the mixer current. A nominal value of 1000Ω set the mixer current to 10mA. External RF bypassing is required. The trace length between the bypass caps and the pin should be minimized. Connect ground sides of caps directly to ground.	
18	VCC5	Supply voltage for IC. External RF bypassing is required. The trace length between the bypass caps and the pin should be minimized. Connect ground sides of caps directly to ground.	
19	LNA1 IN	RF input to LNA1. This pin is internally DC biased and, if it is connected to a device with DC present, should be DC blocked with a capacitor suitable for the frequency of operation.	
20	GND	Ground connection. For best performance, keep traces physically short and connect directly to ground plane.	
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with multiple vias.	

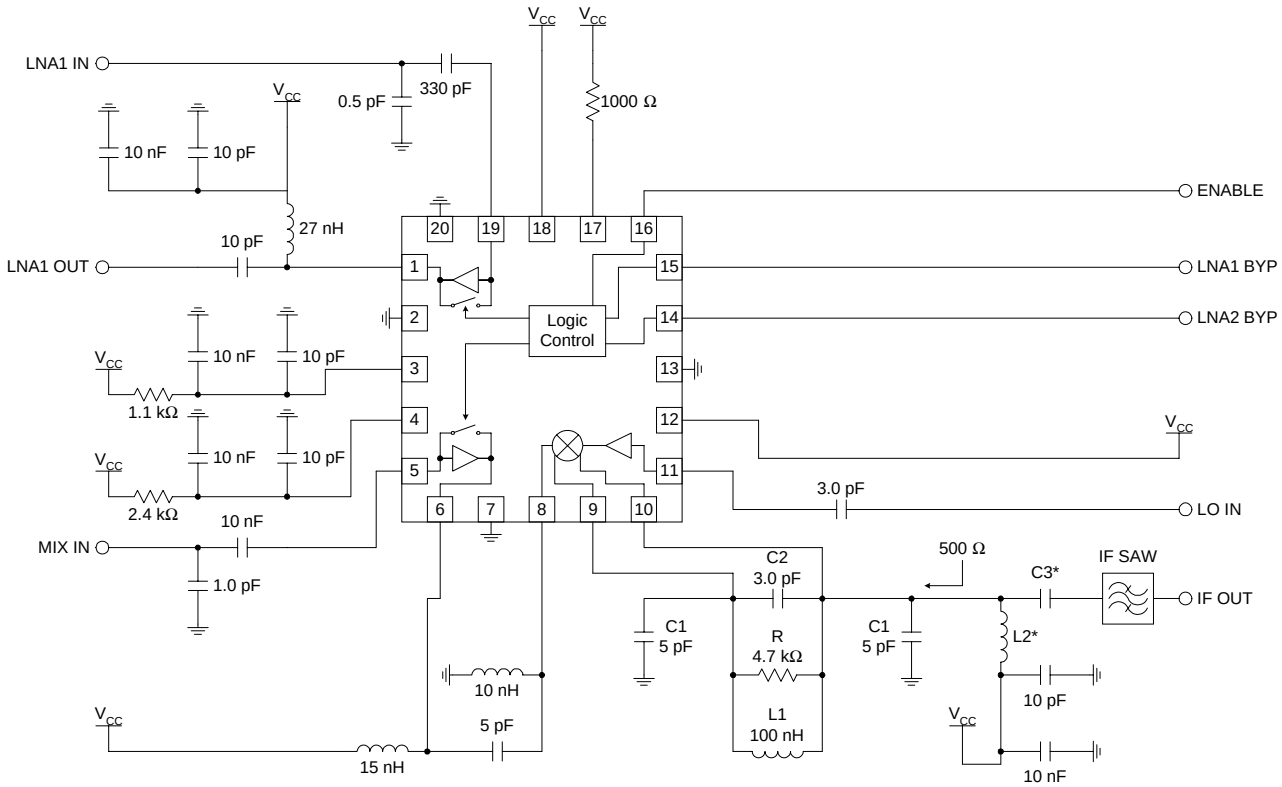
LNA1, LNA2 and Mixer Application Schematic (RF=2140MHz, IF=190MHz)



LNA2 OUT and MIX IN matching network need to be determined. (L3, L4, C4, and C5)

* See output interface network of the mixer to determine L2 and C3.

LNA1, LNA2 Cascade with Mixer Application Schematic (RF=2140MHz, IF=190MHz)



*See output interface network of the mixer to determine L2 and C3.

Output Interface Network of the Mixer

L1, C1, C2, and R form a current combiner which performs a differential to single-ended conversion at the IF frequency and sets the output impedance. In most cases, the resonance frequency is independent of R and can be set according to the following equation:

$$f_{IF} = \frac{1}{2\pi\sqrt{\frac{L1}{2}(C_1 + 2C_2 + C_{EQ})}}$$

Where C_{EQ} is the equivalent stray capacitance and capacitance looking into pins 9 and 10. An average value to use for C_{EQ} is 2.5pF.

R can then be used to set the output impedance according to the following equation:

$$R = \left(\frac{1}{4 \cdot R_{OUT}} - \frac{1}{R_P}\right)^{-1}$$

where R_{OUT} is the desired output impedance and R_P is the parasitic equivalent parallel resistance of L1.

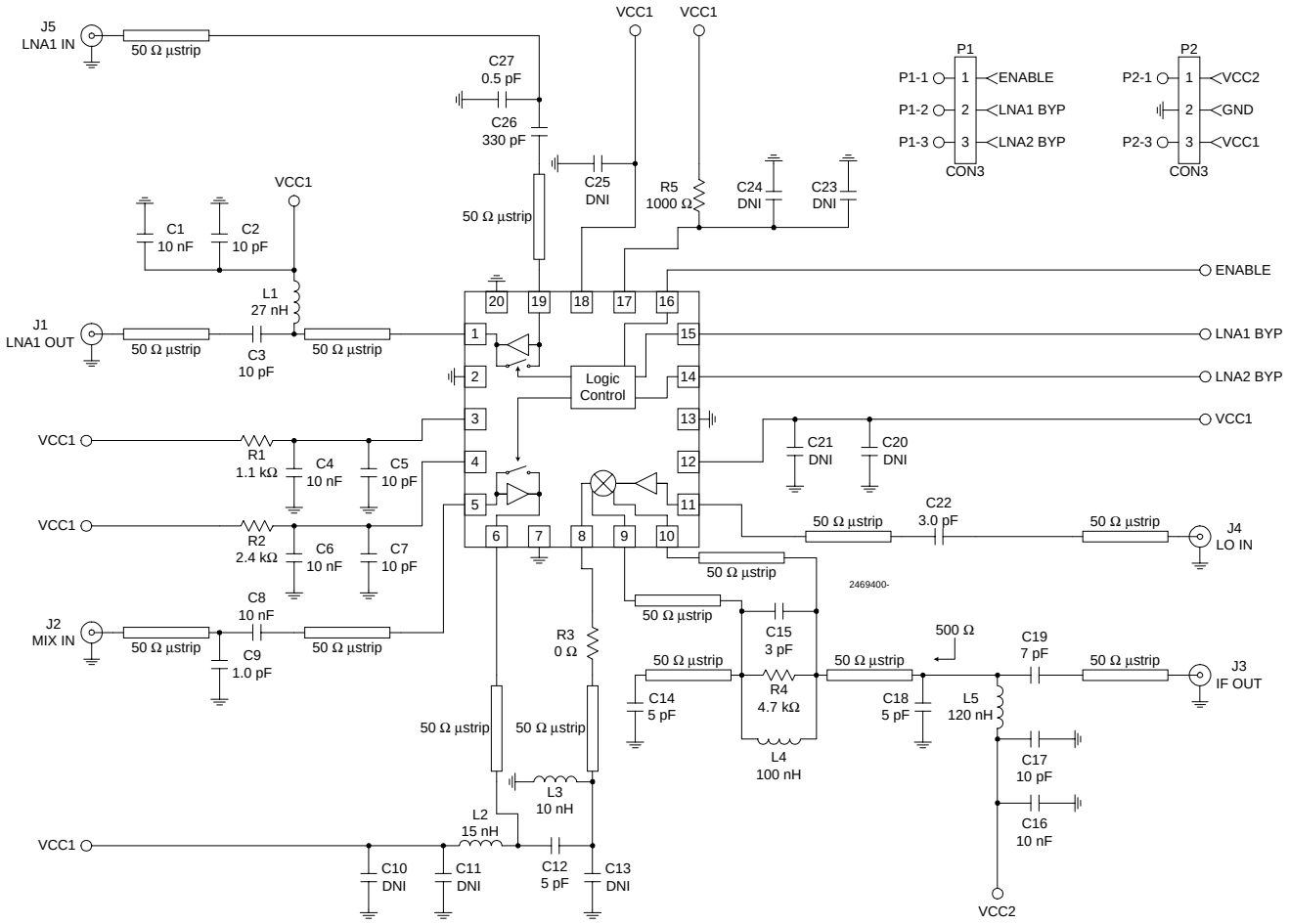
C_2 should first be set to 0 and C1 should be chosen as high as possible, while maintaining an R_P of L1 that allows for the desired R_{OUT}. If the self-resonant frequencies of the selected C1 produce unsatisfactory linearity performance, their values may be reduced and compensated for by including C2 capacitor with a value chosen to maintain the desired F_{IF} frequency.

L2 and C3 serve dual purposes. L2 serves as an output bias choke, and C3 serves as a series DC block.

In addition, L2 and C3 may be chosen to form an impedance matching network if the input impedance of the IF filter is not equal to R_{OUT}. Otherwise, L2 is chosen to be large (suggested 120nH) and C3 is chosen to be large (suggested 22nF) if a DC path to ground is present in the IF filter, or omitted if the filter is DC blocked.

Evaluation Board Schematic
(RF=2140MHz, IF=190MHz)

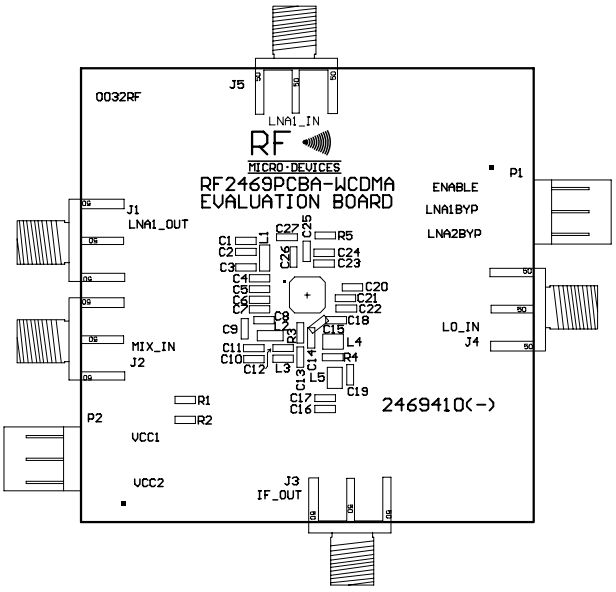
(Download Bill of Materials from www.rfmd.com.)



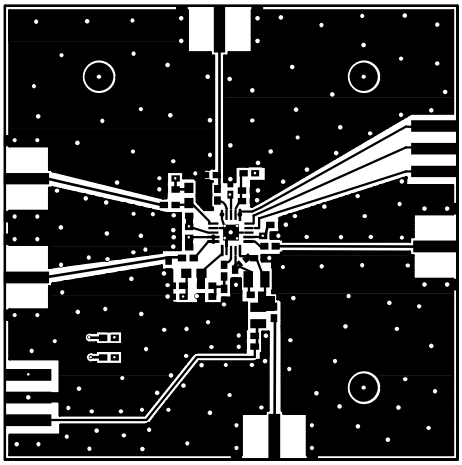
Evaluation Board Layout
Board Size 2.0” x 2.0”

Board Thickness 0.062”, Board Material FR-4, Multi-Layer

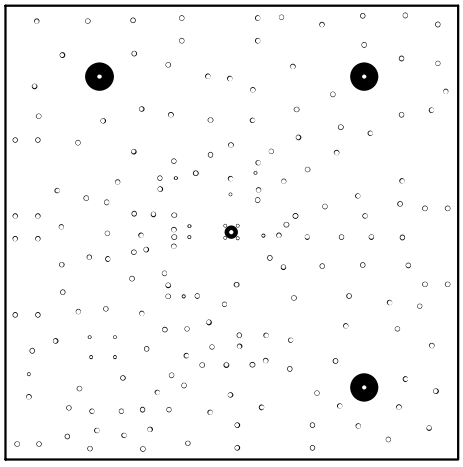
Assembly



Top



Power Plane



Back